

Async Fast Code Information(1/2)

Last Updated : November 2008

<u>K</u>	<u>6</u>	<u>R</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	-	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>
1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18

1. Memory (K)

2. Async Fast SRAM : 6

3. Small Classification

R : Center Vcc/Vss + Fast SRAM

4~5. Density

10 : 1M 40 : 4M

6~7. Organization

04 : x4 08 : x8
16 : x16

8. Vcc

C : 5.0V V : 3.3V

9. Mode

1 : CS Low Active

10. Generation

M : 1st Generation
A : 2nd Generation
B : 3rd Generation
C : 4th Generation
D : 5th Generation

12. Package

A : TBGA (Lead-Free)	C : CHIP BIZ
E : TBGA	F : FBGA
H : BGA	J : SOJ
K : SOJ (Lead-Free)	T : TSOP
U : TSOP2-400 (Lead-Free)	W : WAFER
X : FBGA (Lead-Free)	

13. Temp, Power

- COMMON (Temp, Power)

C : Commercial, Normal

I : Industrial, Normal

- WAFER,CHIP BIZ Level Division

0 : NONE, NONE

1 : Hot DC sort

2 : Hot DC, selected AC sort

3 : Cold/Hot DC, selected AC sort

14~15. Speed (tAA)

- Center Vcc/Vss + Fast SRAM

08 : 8ns 10 : 10ns

Async Fast Code Information(2/2)

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K 6 R X X X X X X X - X X X X X X X
 1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18

16. Packing Type

- Common to all products, except of Mask ROM
- Divided into TAPE & REEL(In Mask ROM, divided into TRAY, AMMO Packing Separately)

Divide	Packing Type	New Marking
Component	TAPE & REEL	T
	Other (Tray, Tube, Jar)	0 (Number)
	Stack	S
Component (Mask ROM)	TRAY	Y
	AMMO PACKING	A
Module	MODULE TAPE & REEL	P
	MODULE Other Packing	M

17~18. Customer "Customer List Reference"